

Package Material Composition and Mass Calculation

Customer:
Package:
Device Type:
Die Size(mm):
Total Pkg. Wt (g): NVL VFQFN 48L 6x6PKG nRF52832-QFAA#6X

2.976x3.246 0.11080

Provided By : Date : Doris 2015/12/17

Rev.:

	name	vendor	material composition	CAS No.	%	mg.(ave)	mg.	%	PPM
Mold Compound	CEL-9240HF	HITACHI					<u>47.15</u>	42.556%	425,564
			Solid Epoxy Resin-1	Trade secret		3.06482		2.766%	27,662
			Solid Epoxy Resin-2	Trade secret	≦2%	0.37721		0.340%	3,405
			Solid Epoxy Resin-3	Trade secret	≦8%	1.41453		1.277%	12,767
			Phenol Resin	Trade secret	≦8%	1.88604		1.702%	17,023
			Carbon black	1333-86-4	Approx. 0.2%	0.09430		0.085%	851
			Amorphous silica	60676-86-0	78-92%	39.60684		35.747%	357,473
			Crystal silica	14808-60-7	<5%	0.70727		0.638%	6,383
Leadframe	C194_Ag	MITSUI					<u>54.79</u>	49.449%	494,492
			Copper(Cu)	7440-50-8	92.05-97.835%	52.71709		47.580%	475,801
			Iron(Fe)	7439-89-6	2.1-2.6%	1.28752		1.162%	11,621
			Zinc(Zn)	7440-66-6	0.05-0.2%	0.07122		0.064%	643
			Phrosphorus(P)	7723-14-0	0.015-0.15%	0.04383		0.040%	396
			Silver(Ag)	7440-22-4	5.0%Max.	0.66841		0.603%	6,033
Die_1	Silicon		Silicon	7440-21-3	100%		<u>5.89</u>	5.315%	53,150
Die Attach_1	EN-4900G*	HITACHI					0.83	0.753%	7,530
			Silver(Ag)	7440-22-4	72-82%	0.61734		0.557%	5,572
			Acrylic resin	Trade secret	6-11%	0.07508		0.068%	678
			Polybutadiene derivative	Trade secret	2-9%	0.04171		0.038%	376
			Butadiene copolymer	Trade secret	< 2.0 %	0.01251		0.011%	113
			Acrylate	Trade secret	3-8%	0.05005		0.045%	452
			Epoxy resin	Trade secret	1-4%	0.02086		0.019%	188
			Peroxide	Trade secret	< 1.0%	0.00417		0.004%	38
			Additive	Trade secret	< 2.0%	0.01251		0.011%	113
Wire_1	3N_Cu wire	NIPPON					0.28	0.251%	2,507
			Copper(Cu)	7440-50-8	≥96.9%	0.27741		0.2504%	2,504
			Palladium(Pd)	7440-05-3	≤3.1%	0.00033		0.0003%	3
External Plating	Sn plating	SHENMAO					<u>1.86</u>	1.676%	16,758
			Tin(Sn)	7440-31-5	>99.97%	1.85674		1.676%	16,758
Total							110.80	100%	1000000

- The above material declaration can be used only as reference in identifying the Hazardous material content of the product.

 ASE does not guarantee the Material composition accuracy as it is based on the data provided by outside sources and has not been validated.

 This material declaration does not include data from any active and passive component assembled in the package.

 Due to Leadframe and substrate is belong "re-make product" by other homogeneous material, so it's composition will be different with MSDS